



Product Change Notification



Product Group: SIL/Fri Oct 22, 2021/PCN-SIL-000411-2021-REV-0

Additional Capacity for SO16, TSSOP16 and TDFN4 packages

DESCRIPTION OF CHANGE: Vishay Siliconix has expanded assembly capacity for SO16, TSOP16 and TDFN4 packages to Subcontractor UTAC in Thailand.

REASON FOR CHANGE: Addition of assembly capacity

EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE: There will be no effect on performance, quality or reliability.

PART NUMBERS/SERIES/FAMILIES AFFECTED: Please see materials list on the succeeding page.

VISHAY BRAND(s): Vishay Siliconix

TIME SCHEDULE:

Start Shipment Date: Wed Feb 2, 2022

SAMPLE AVAILABILITY: November 1, 2021

PRODUCT IDENTIFICATION: Date Code and Lot Code

QUALIFICATION DATA: See PDF attached

This PCN is considered approved, without further notification, unless we receive specific customer concerns before Wed Feb 2, 2022 or as specified by contract.

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For further information, please contact your regional Vishay office.

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ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENT



Product Change Notification



Product Group: SIL/Fri Oct 22, 2021/PCN-SIL-000411-2021-REV-0

DG4051EEY-T1-GE3	DG4052EEY-T1-GE3	DG4053EEY-T1-GE3	DG408LEDY-GE3	DG408LEDY-T1-GE3
DG409LEDY-GE3	DG409LEDY-T1-GE3	DG411LEDY-GE3	DG411LEDY-T1-GE3	DG412LEDY-GE3
DG412LEDY-T1-GE3	DG413LEDY-GE3	DG413LEDY-T1-GE3	DG441LEDY-GE3	DG441LEDY-T1-GE3
DG442LEDY-GE3	DG442LEDY-T1-GE3	DG611EEY-T1-GE4	DG612EEY-T1-GE4	DG613EEY-T1-GE4
DG1411EEQ-T1-GE4	DG1412EEQ-T1-GE4	DG1413EEQ-T1-GE4	DG4051EEQ-T1-GE3	DG4052EEQ-T1-GE3
DG4053EEQ-T1-GE3	DG408LEDQ-GE3	DG408LEDQ-T1-GE3	DG409LEDQ-GE3	DG409LEDQ-T1-GE3
DG411LEDQ-T1-GE3	DG441LEDQ-GE3	DG441LEDQ-T1-GE3	DG442LEDQ-GE3	DG442LEDQ-T1-GE3
DG611EEQ-T1-GE4	DG612EEQ-T1-GE4	DG613EEQ-T1-GE4	DG636EEQ-T1-GE4	DG9424EDQ-T1-GE3
DG9425EDQ-T1-GE3	DG9426EDQ-T1-GE3	DG411LEDQ-GE3	DG412LEDQ-T1-GE3	DG412LEDQ-GE3
DG413LEDQ-T1-GE3	DG413LEDQ-GE3	SIP32401ADNP-T1GE4	SIP32402ADNP-T1GE4	SIP32408DNP-T1-GE4
SIP32409DNP-T1-GE4	SIP32411DNP-T1-GE4	SIP32431DNP3-T1GE4	SIP32432DNP3-T1GE4	SIP32448DNP-T1-GE4
SIP4282ADNP3-T1GE4	SIP4282DNP3-T1GE4			

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PCN_SIL-4112021 QUALIFICATION DATA

TDFN4, TSSOP16 packages

**UTAC Thailand
Qualification Data**

October 2021



PCN_SIL-4112021 QUALIFICATION DATA

TDFN4 DATA

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC		FAIL	DONE	TEST	FAIL
*****	*****	****	*****	/VOLT	SS	****	****	TYPE	CODE
*****	*****	****	*****	*****	*****	****	****	****	****
2160007	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	C-SAM & PR	0	C-SAM & PRECO	0	11	0	X	VM	
		1	C-SAM & PRECO	192	11	0	X	VM	
		0	DPA	0	45	0	X	VM	
	PHYSICAL D	0	PHYSICAL DIM	0	30	0	X	VM	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	

PART NUMBER: AMSIP32402A
 GEOMETRY: PABV-B
 LOT #: M28Q001.3
 DATE CODE: 82047
 PURPOSE: QUAL

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC		FAIL	DONE	TEST	FAIL
*****	*****	****	*****	/VOLT	SS	****	****	TYPE	CODE
*****	*****	****	*****	*****	*****	****	****	****	****
2160008	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	C-SAM & PR	0	C-SAM & PRECO	0	11	0	X	VM	
		1	C-SAM & PRECO	192	11	0	X	VM	
		0	DPA	0	45	0	X	VM	
	PHYSICAL D	0	PHYSICAL DIM	0	30	0	X	VM	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	

PART NUMBER: AMSIP32402A
 GEOMETRY: PABV-B
 LOT #: M33Q005B.
 DATE CODE: 82047
 PURPOSE: QUAL



PCN_SIL-4112021 QUALIFICATION DATA

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC	/VOLT SS	FAIL	DONE	TEST	FAIL
*****	*****	***	*****	*****	*****	****	****	****	****
2160009	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	C-SAM & PR	0	C-SAM & PRECO	0	11	0	X	VM	
		1	C-SAM & PRECO	192	11	0	X	VM	
	DPA	0	DPA	0	45	0	X	VM	
	PHYSICAL D	0	PHYSICAL DIM	0	30	0	X	VM	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	

PART NUMBER: AMSIP32402A
 GEOMETRY: PABV-B
 LOT #: M28Q005B.
 DATE CODE: 82047
 PURPOSE: QUAL



TSSOP16 DATA

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC	/VOLT	S S	FAIL	DONE	TEST TYPE	FAIL CODE
*****	*****	****	*****	*****	*****	****	****	****	****	****
2060068	BOND INT	0	BOND INT	0	40	0	X	VM		
		1	BOND INT	250	40	0	X	VM		
		2	BOND INT	500	40	0	X	VM		
	C-SAM & PR	0	C-SAM & PRECO	0	11	0	X	VM		
		1	C-SAM & PRECO	192	11	0	X	VM		
	DAMP HEAT	0	DAMP-HEAT-50C	0	55	0	X	ET		
		1	DAMP-HEAT-50C	96	55	0	X	ET		
	ESD - C D	0	ESD' - C D MO	0	30	0	X	ET		
		1	ESD' - C D MO	125	82	0	X	ET		
		2	ESD' - C D MO	250	3	0	X	ET		
		3	ESD' - C D MO	500	3	0	X	ET		
			4	ESD' - C D MO	750	3	0	X	ET	
			5	ESD' - C D MO	1000	3	0	X	ET	
			6	ESD' - C D MO	1500	3	0	X	ET	
			7	ESD' - C D MO	2000	3	0	X	ET	
	ESD - H B	0	ESD' - H B MO	0	30	0	X	ET		
		1	ESD' - H B MO	125	3	0	X	ET		
		2	ESD' - H B MO	250	3	0	X	ET		
		3	ESD' - H B MO	500	3	0	X	ET		
		4	ESD' - H B MO	750	3	0	X	ET		
		5	ESD' - H B MO	1000	3	0	X	ET		
		6	ESD' - H B MO	1500	3	0	X	ET		
		7	ESD' - H B MO	2000	3	0	X	ET		
		8	ESD' - H B MO	2500	3	0	X	ET		
			9	ESD' - H B MO	3000	3	0	X	ET	
	EXT VISUAL	0	EXT VISUAL	0	15	0	X	VM		
		HAST	0	HAST	0	82	0	X	ET	
			1	HAST	100	82	0	X	ET	
	PRESSURE P	0	PRESSURE POT	0	82	0	X	ET		
		1	PRESSURE POT	96	82	0	X	ET		
	S S OP LIF	0	HIGH TEMP OP	0	82	0	X	ET		
		1	HIGH TEMP OP	168	82	0	X	ET		
SOLDER DUN	0	SOLDER DUNK	0	55	0	X	VM			
	1	SOLDER DUNK	10	55	0	X	ET			
SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM			
	TEMP CYCLE	0	T/C (H)	0	82	0	X	ET		
		1	T/C (H)	250	82	0	X	ET		
		2	T/C (H)	500	82	0	X	ET		
VP/SOLDER	0	PRODUCT PRECO	0	400	0	X	ET			
	1	PRODUCT PRECO	192	400	0	X	ET			
VALIDATION	0	REFLOW+250CYS	0	3000	0	X	ET			
	1	REFLOW+250CYS	250	3000	0	X	ET			

PART NUMBER: DG1413EEQ
 GEOMETRY: DAAA-C
 LOT ID: K19B001A.5
 DATE CODE:
 PURPOSE: QUALIFICATION



PCN_SIL-4112021 QUALIFICATION DATA

EVAL	STRESS	HR/CYC	TEST CONDITION	TEST	FAIL	FAIL	DONE	TYPE	CODE	
*****	*****	****	*****	*****	****	****	****	****	****	
2060069	BOND INT	0	BOND INT	0	40	0	X	VM		
		1	BOND INT	250	40	0	X	VM		
		2	BOND INT	500	40	0	X	VM		
	C-SAM & PR	0	C-SAM & PRECO	0	11	0	X	VM		
		1	C-SAM & PRECO	192	11	0	X	VM		
	DAMP HEAT	0	DAMP-HEAT-50C	0	55	0	X	ET		
		1	DAMP-HEAT-50C	96	55	0	X	ET		
	EXT VISUAL	0	EXT VISUAL	0	15	0	X	VM		
		1	HAST	0	82	0	X	ET		
	HAST	0	HAST	0	82	0	X	ET		
		1	HAST	100	82	0	X	ET		
	PRESSURE P	0	PRESSURE POT	0	82	0	X	ET		
		1	PRESSURE POT	96	82	0	X	ET		
	S S OP LIF	0	HIGH TEMP OP	0	82	0	X	ET		
		1	HIGH TEMP OP	168	82	0	X	ET		
	SOLDER DUN	0	SOLDER DUNK	0	55	0	X	ET		
		1	SOLDER DUNK	10	55	0	X	ET		
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM		
		TEMP CYCLE	0	T/C (H)	0	82	0	X	ET	
			1	T/C (H)	250	82	0	X	ET	
	VP/SOLDER	0	T/C (H)	500	82	0	X	ET		
		1	PRODUCT PRECO	0	300	0	X	ET		
	VALIDATION	1	PRODUCT PRECO	192	300	0	X	ET		
		0	REFLOW+250CYS	0	3000	0	X	ET		
	1	REFLOW+250CYS	250	3000	0	X	ET			

PART NUMBER: DG412LEDQ
 GEOMETRY: PBADB
 LOT ID: K40Q001B.21
 DATE CODE:
 PURPOSE: QUALIFICATION

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